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SEMICONDUCTOR



ESD



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GDT



PLED

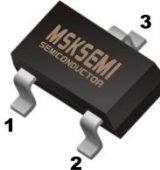

MMBT2222A-MS

Product specification

FEATURES

- Epitaxial planar die construction
- Complementary PNP Type available(MMBT2907A-MS)

Reference News

PACKAGE OUTLINE	MARKING
 <p>1. BASE 2. EMITTER 3. COLLECTOR</p>	
SOT-23	

MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{CB0}	Collector-Base Voltage	75	V
V_{CEO}	Collector-Emitter Voltage	40	V
V_{EBO}	Emitter-Base Voltage	6	V
I_C	Collector Current -Continuous	600	mA
P_C	Collector Dissipation	300	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	417	°C/W
T_J, T_{stg}	Operation Junction and Storage Temperature Range	-55~+150	°C

ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

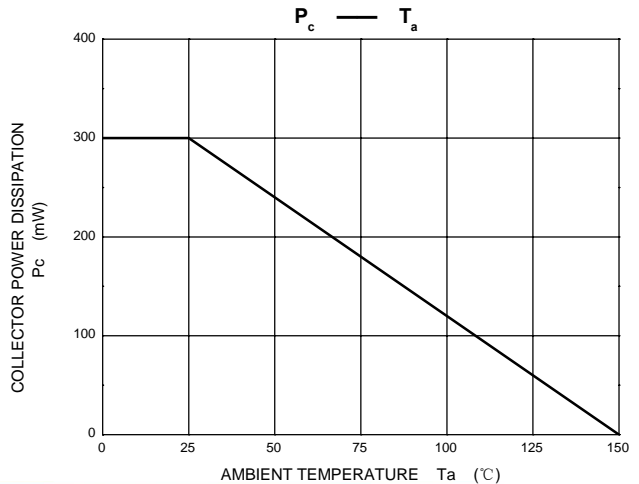
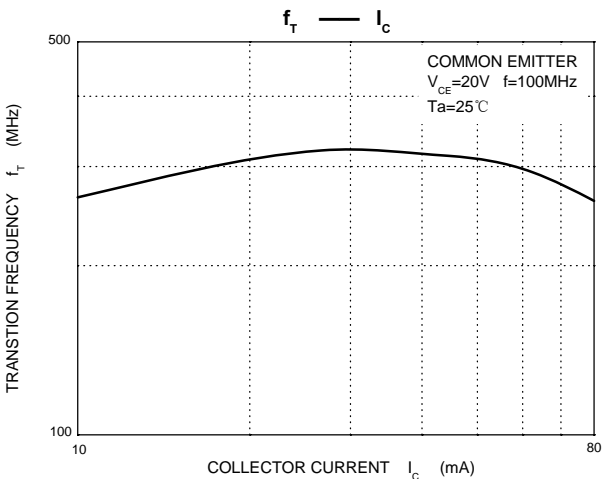
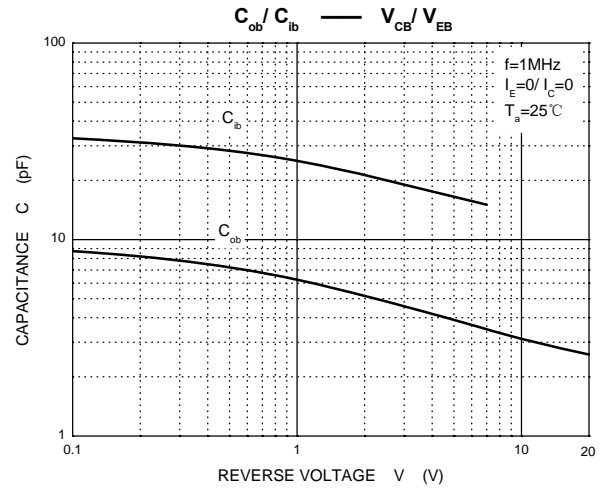
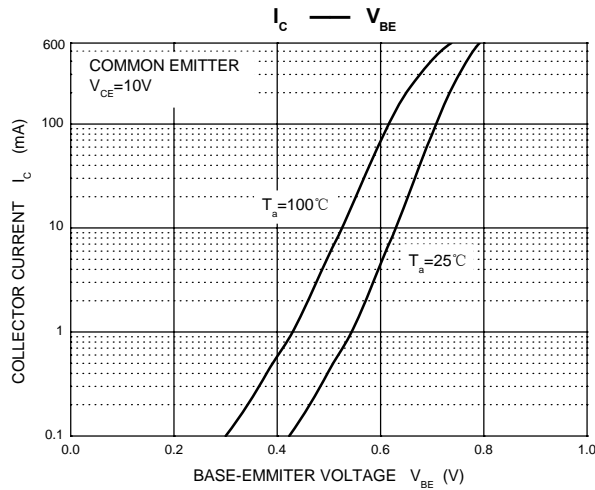
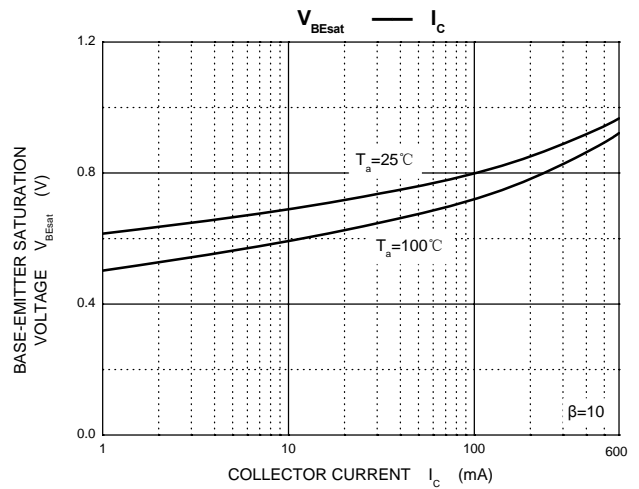
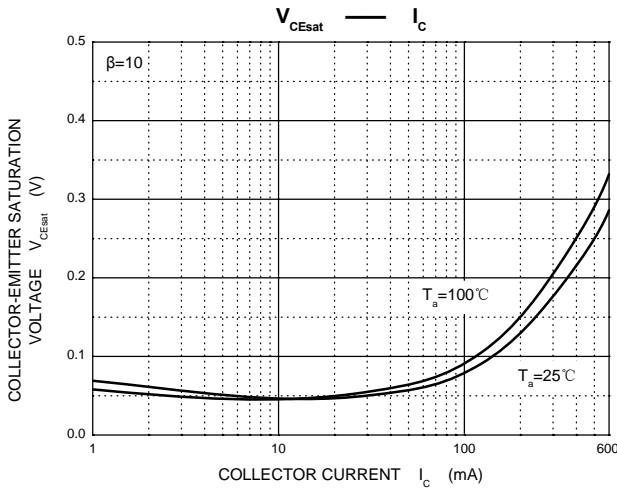
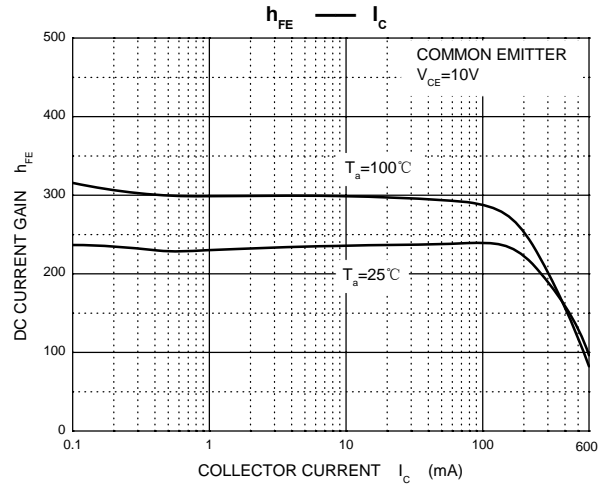
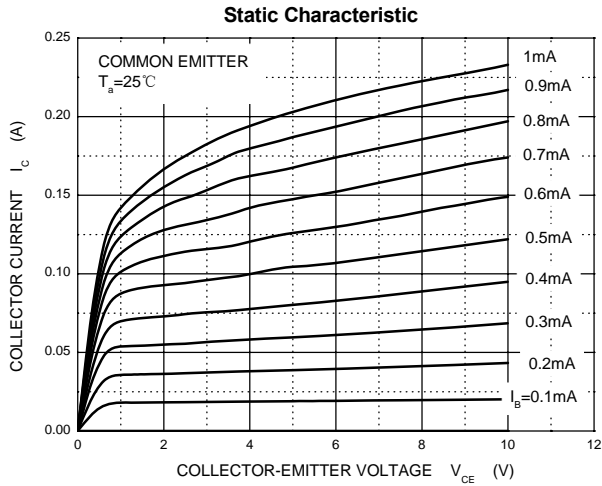
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C = 10\mu A, I_E = 0$	75			V
Collector-emitter breakdown voltage	$V_{(BR)CEO}^*$	$I_C = 10mA, I_B = 0$	40			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E = 10\mu A, I_C = 0$	6			V
Collector cut-off current	I_{CBO}	$V_{CB} = 60V, I_E = 0$			0.01	μA
Collector cut-off current	I_{CEX}	$V_{CE} = 30V, V_{BE(off)} = 3V$			0.01	μA
Emitter cut-off current	I_{EBO}	$V_{EB} = 3V, I_C = 0$			0.1	μA
DC current gain	$h_{FE(1)}^*$	$V_{CE} = 10V, I_C = 150mA$	100		300	
	$h_{FE(2)}^*$	$V_{CE} = 10V, I_C = 0.1mA$	40			
	$h_{FE(3)}^*$	$V_{CE} = 10V, I_C = 500mA$	42			
Collector-emitter saturation voltage	$V_{CE(sat)}^*$	$I_C = 500mA, I_B = 50mA$ $I_C = 150mA, I_B = 15mA$			1 0.3	V
Base-emitter saturation voltage	$V_{BE(sat)}^*$	$I_C = 500mA, I_B = 50mA$ $I_C = 150mA, I_B = 15mA$			2.0 1.2	V
Transition frequency	f_T	$V_{CE} = 20V, I_C = 20mA, f = 100MHz$	300			MHz
Delay time	t_d	$V_{CC} = 30V, V_{BE(off)} = -0.5V$ $I_C = 150mA, I_{B1} = 15mA$			10	ns
Rise time	t_r				25	ns
Storage time	t_s	$V_{CC} = 30V, I_C = 150mA$ $I_{B1} = -I_{B2} = 15mA$			225	ns
Fall time	t_f				60	ns

*pulse test: Pulse Width $\leq 300\mu s$, Duty Cycles $\leq 2.0\%$.

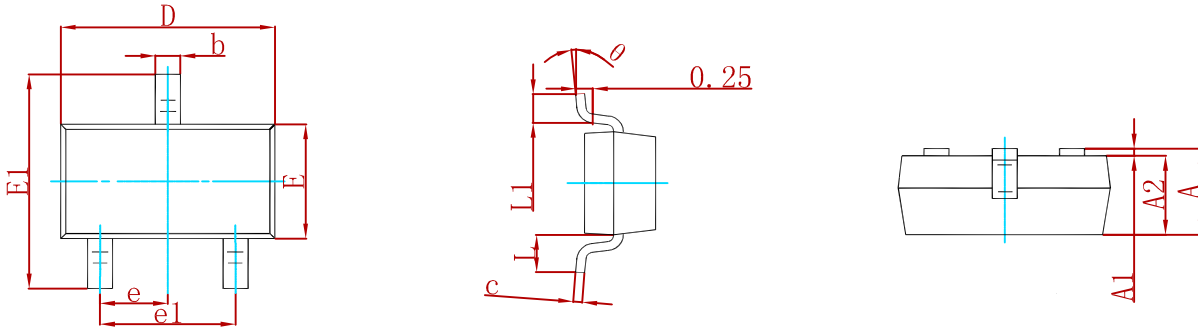
CLASSIFICATION OF $h_{FE(1)}$

RANK	L	H
RANGE	100 –200	200 –300

Typical Characteristics

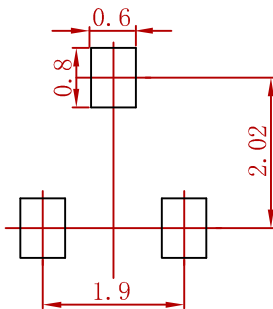


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
 1. Controlling dimension; in millimeters.
 2. General tolerance: ± 0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MMBT2222A-MS	SOT-23	3000

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